

FEATURES

- → Glass passivated device
- ◆ Ideal for surface mouted applications
- ◆ Low reverse leakage
- Metallurgically bonded construction
- ◆ High temperature soldering guaranteed: 250°C/10 seconds,0.375" (9.5mm) lead length, 5 lbs. (2.3kg) tension

MECHANICAL DATA

Case: JEDEC SOD-123FL molded plastic body over passivated chip

Terminals: Plated axial leads, solderable per MIL-STD-750,

Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any Weight: 0.0007 ounce, 0.02 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

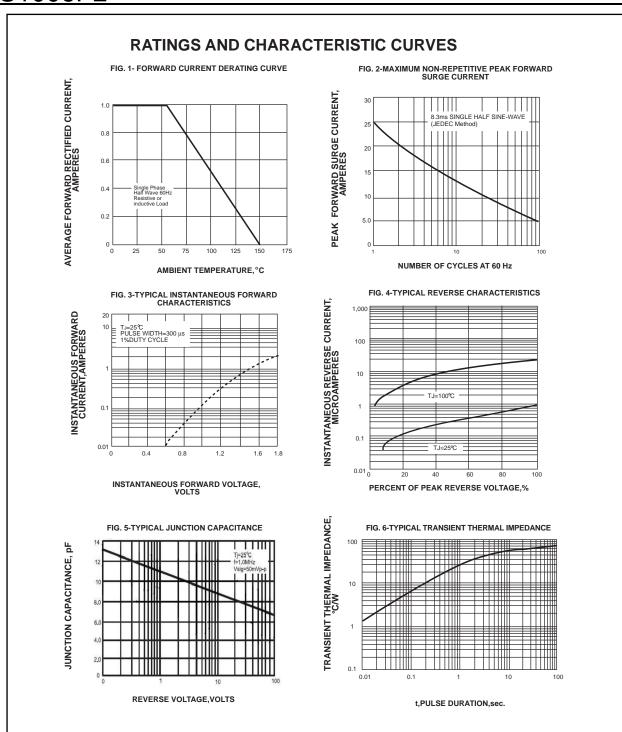
Catalog Number	SYMBOLS	ES1006FL	UNITS
Maximum repetitive peak reverse voltage	Vrrm	600	VOLTS
Maximum RMS voltage	VRMS	420	VOLTS
Maximum DC blocking voltage	VDC	600	VOLTS
Maximum average forward rectified current	l(AV)	1.0	Amp
Peak forward surge current			
8.3ms single half sine-wave superimposed on	IFSM	25.0	Amps
rated load (JEDEC Method)			
Maximum instantaneous forward voltage at1.0A	VF	1.7	Volts
Maximum DC reverse current Ta=25℃	lr	5.0	μΑ
at rated DC blocking voltage Ta=100℃		100.0	
Maximum reverse recovery time (NOTE 1)	trr	35	ns
Typical junction capacitance (NOTE 2)	Сл	10	pF
Typical thermal resistance (NOTE 3)	Reja	85	K/W
Operating junction and storage temperature range	ТЈ,Тѕтс	-55 to +150	°C

Note: 1.Measured with IF=0.5A, IR=1A, Irr=0.25A.

2. Measured at 1MHz and applied reverse voltage of 4.0V D.C. 3.PCB mounted on 0.2*0.2" (5.0*5.0mm) coppeer pad area.

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